IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
upplier Info	rmation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2023-06-12			
Contact Name		·	Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Ste	ewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorized Repr	esentative*		Title - Representative			I	Phone - Representative*			Email - Representative*				
Product-Env-Ste	ewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Reque	ester Item Number			Mfr Item Name			Effective Date	Version	n I	Manufacturing Site	W	eight*	UOM	Unit Type
				2 CH. ESD PROTE	SD PROTECTION		2023-06-12 CNQ		CNQ	1.	384954	mg	Each	
Ianufacturin	ng Proccess Informa	tion											·	·
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL	ASL Rating Peak Process Body Temperature Max Time at Peak					Temperatu	e Numb	er of Reflow Cyc	eles	
SnAgCu		C	CU Alloy 1			260 C 30		30	second	3				
omments														
vel 1 - maximun	n time at peak temperatı	are during sol	dering is 10-3	30 seconds										
or more informa	ation regarding material	composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's slability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Backside Protection Film	ackside Protection Film 0.022118			Epoxy resin	proprietary data		0.0046	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0004	mg
			Supplier	Acrylic resins	Proprietary Data		0.0046	mg
			Supplier	Silica (SiO2)	14464-46-1		0.0125	mg
Die	0.860424		Supplier	Silicon (Si)	7440-21-3		0.8594	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0011	mg
Solder Ball	0.465499	mg	Supplier	Silver (Ag)	7440-22-4		0.0121	mg
			Supplier	Tin (Sn)	7440-31-5		0.4506	mg
			Supplier	Copper (Cu)	7440-50-8		0.0028	mg
Under Bump Metal	0.036913	mg	Supplier	Titanium (Ti)	7440-32-6		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.0367	mg